

## ABOUT ME

I am an enthusiastic SoC Researcher, with Physical Design expertise and a keen eye for design methodologies. I thrive in contexts where "what?" is always followed by "how?". Currently, I am looking for a chance to boost my knowledge on Computer Architectures while leveraging my expertise in SoC design. My ambition is to steer the semiconductor industry towards the path of Architecture-Design Co-Optimization, as I strongly believe that it will be a key enabler for next generation digital ICs.

## EDUCATION

Doctor of Philosophy (PhD), Electrical Engineering

Ecole polytechnique de Bruxelles – Université Libre de Bruxelles

Oct 2018 – Oct 2021(expected) Leuven, BE

- Thesis: "Design Enablement of integrated circuits using sub-5nm technology process and 3D integration"

Exchange Student, Electronic Systems

Department of Electrical Engineering – Technology University of Eindhoven

Feb 2017 – July 2017 Eindhoven, NL

- Projects: RISC microprocessor design • interconnection network modelling for a multicore processor • embedded controller design for automotive (Xilinx FPGA) • low power RF mixer design

MSc, Electrical Engineering, Micro Electronics Systems

Dipartimento di Ingegneria Elettrica e dell'informazione – Politecnico di Bari

Jan 2016 – Jul 2018 Bari, IT

## EXPERIENCE

PhD Candidate

Cadence Design Systems - IMEC

Oct 2018 – Present Leuven, BE

- Proposal and implementation of new methods to enable advanced technologies for front-end and back-end digital IC design
- Advanced CMOS technology nodes (sub-5nm): FinFET • GAAFET • CFET
- 3D-IC: Face-to-Face Hybrid Bonding stacking
- Industrial design benchmarking: ARM • RISC-V • NVDLA

Engineering Internship

Huawei Technologies

Feb 2018 – Jul 2018 Sophia-Antipolis, FR

- Architecture design and physical implementation of digital filters for All Digital PLLs

Event organizing team

Devlounge

Sep 2016 – Nov 2016 Bari, IT

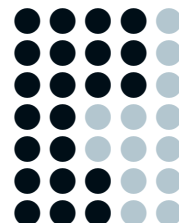
- Technical support to comics convention: Hardware management • Ordering service

## LIST OF PUBLICATIONS

- G.Sisto, P. Debacker, R. Chen, G. van Der Plaas, R. Chou, E. Beyne, D. Milojevic, Design enablement of fine pitch face-to-face 3D system integration using die-by-die place & route, 3DIC 2019, Sendai, Japan

## TECHNICAL SKILLS

TCL  
Bash  
Linux  
Verilog, VHDL  
Python  
Git  
Matlab



## SOFT SKILLS

Resilience Problem solving  
Project management Empathy  
Affinity to learn Team player  
Public Speaking/Presenting

## LANGUAGES

Italian  
English  
French  
Dutch



## AWARDS

ERASMUS+ for Traineeship  
Scholarship

TUCEP

2018 Bari, IT

ERASMUS+ Scholarship  
Politecnico di Bari

2017 Bari, IT

## INTERESTS

Videogames Board/Card games  
eSports Football Cinema  
Travel Music